

300-Millimeter-Halbleiterwerk Dresden

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- Total investment approx. 1 billion euros
- Site approx. 100,000 m²
- Total floor space approx. 72,000 m² of production area and office space
- Clean-room area Currently approx. 10,000 m², addition of some 3,000 m²
- Associates roughly 480 in August 2023
- Qualified professionals needed Experts from the semiconductor industry, such as process, production or maintenance engineers, mathematicians, software engineers as well as professionals and graduates with degrees in physics, chemistry, or microsystems technology
- Manufacturing technology Highly automated wafer production (300mm silicon substrate wafers with structures up to 65nm in width)
- Manufactured products Application-specific integrated circuits (ASICs) and power semiconductors

MEMS manufacturing on 300mm wafers (SOP in 2026)
- Fields of application for semiconductors Mainly automotive electronics and industrial applications

- Connected manufacturing At the wafer fab in Dresden, production data is generated at a rate of 250 MB/second, which corresponds to the data volume of 400 HD videos running simultaneously.
- Funding Construction of the new wafer fab in Dresden received funding as part of IPCEI 1 Microelectronics (Important Project of Common European Interest) from the German federal government – more specifically, the Federal Ministry for Economic Affairs and Climate Action (BMWK).

Over the next years, Bosch plans to invest some three billion euros in Dresden and Reutlingen, both as part of its own investment plan and under the auspices of the European IPCEI ME (“Important Project of Common European Interest on Microelectronics”) funding program.